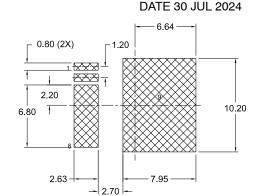


H-PSOF8L 9.90x10.38x2.30, 1.20P CASE 100DC ISSUE D (2x) a ccc В D2 (2x) TERMINAL 1 CORNER INDEX AREA <u></u> E2 (2x) -/7\ SECTION "A-A" SCALE: 2X -(DATUM A) ¬(4X) Ө b (8x) d bbbM C A B D4 (2x) ddd(M) C L2 (8x) ·L1 🙆 **DETAIL "B" TOP VIEW** SCALE: 2X DETAIL "B" SIDE VIEW D1 D5 (2x) D6 D3 (2x) (2x)



RECOMMENDATION *FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

I AND PATTERN

- NOTES:

 1. PACKAGE STANDARD REFERENCE: JEDEC MO-299, ISSUE B.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
- 3. "e" REPRESENTS THE TERMINAL PITCH.
- 4. THIS DIMENSION INCLUDES ENCAPSULATION THICKNESS "A1", AND PACKAGE BODY THICKNESS, BUT DOES NOT INCLUDE ATTACHED FEATURES, e.g., EXTERNAL OR CHIP CAPACITORS. AN INTEGRAL HEATSLUG IS NOT CONSIDERED AS ATTACHED FEATURE. 5. A VISUAL INDEX FEATURE MUST BE LOCATED WITHIN THE HATCHED AREA.
- 6. DIMENSIONS b1,L1,L2 APPLY TO PLATED TERMINALS.
- 7. THE LOCATION AND SIZE OF EJECTOR MARKS ARE OPTIONAL. 8. THE LOCATION AND NUMBER OF FUSED LEADS ARE OPTIONAL.

DIM	MILLIMETERS			
Diivi	MIN.	NOM.	MAX.	
Α	2.20	2.30	2.40	
A1	1.70	1.80	1.90	
b	0.70	0.80	0.90	
b1	9.70	9.80	9.90	
b2	0.35	0.45	0.55	
С	0.40	0.50	0.60	
D	10.28	10.38	10.48	
D/2	5.09	5.19	5.29	
D1	10.98	11.08	11.18	
D2	3.20	3.30	3.40	
D3	2.60	2.70	2.80	
D4	4.45	4.55	4.65	
D5	3.20	3.30	3.40	
D6	0.55	0.65	0.75	
Е	9.80	9.90	10.00	
E1	7.30	7.40	7.50	
E2	0.30	0.40	0.50	
E3	7.40	7.50	7.60	
E4	8.20	8.30	8.40	

DIM	MILLIMETERS			
	MIN.	NOM.	MAX.	
E5	9.36	9.46	9.56	
E6	1.10	1.20	1.30	
E7	0.15	0.18	0.21	
е	1.20 BSC			
e/2	0.60 BSC			
Н	11.58	11.68	11.78	
H/2	5.74	5.84	5.94	
H1	7.15 BSC			
L	1.63	1.73	1.83	
L1	0.60	0.70	0.80	
L2	0.50	0.60	0.70	
L3	0.43	0.53	0.63	
θ	10° REF			
Θ1	10° REF			
aaa	0.20			
bbb	0.25			
CCC	0.20			
ddd	0.20			
eee	0.10			

XXXX = Specific Device Code Α = Assembly Location

D/2

H/2

H1

BOTTOM VIEW

(3x)

E1 E3 E4 E5

HEAT SLUG TERMINAL

= Year WW = Work Week

= Assembly Lot Code

AYWWZZ XXXXXXX XXXXXXX

GENERIC

MARKING DIAGRAM*

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	H-PSOF8L 9.90x10.38x2.30, 1.20P		PAGE 1 OF 1	

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L3

(DATUM A)

_ b2 (8x)

/8\

L (8x)

(DATUM B)-